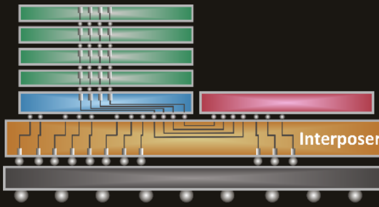
ACCELERATE YOUR IC DESIGN



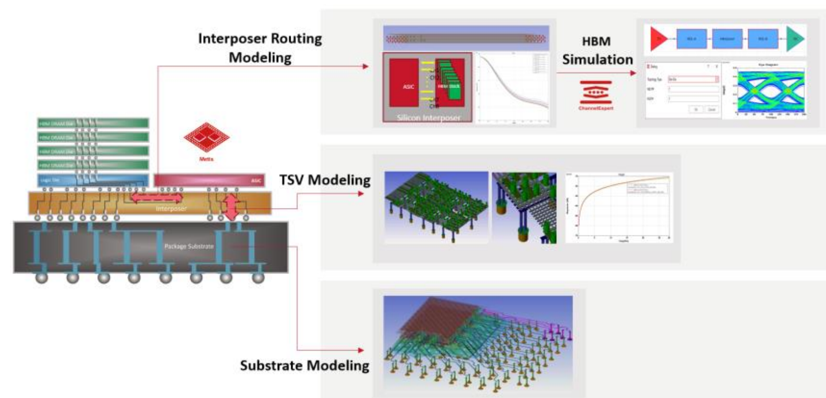
2.5D/3D IC Advanced Packaging Analysis Platform

Highlights

1. While Moore's Law continues driving transistor scaling, heterogeneous integration enabled by 2.5D silicon interposer and HBM becomes the norm for next generation HPC applications.
2. Silicon interposer with RDL and Through-Silicon-Via (TSV) sitting between IC and package requires cross-domain solution to tackle the signal integrity (SI) problems.
3. Xpeedic provides multiple SI analysis tools for 2.5D silicon interposer and HBM applications.
4. TmlExpert helps designer to study transmission line configuration in pre-layout stage, microstrip vs stripline, SGS vs coplanar ground, line-spacing for target impedance, etc.
5. Metis accurately and efficiently extracts interconnect model for both HBM and die-package TSV channels.
6. ChannelExpert helps designer to quickly build high-speed channel, run channel simulation, and check channel performance against compliance specs.

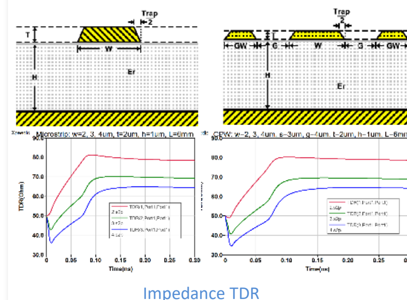
Design Solution for 2.5D Silicon Interposer and Substrate

- Large-capacity EM solver to enable multi-die 2.5D/3D IC SI/PI analysis
- High-Speed Memory I/O Path: a large number of transmission lines on meshed ground plane need accurate and unified extraction for signal integrity.
- High-Speed Serial I/O Path: accurate TSV model is critical for signal integrity.



Transmission Line Design

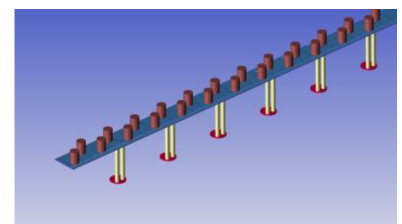
- TmlExpert has built-in interposer transmission line template to help designers to explore different configurations in terms of impedance, loss, delay, skew, and TDR.



Impedance TDR

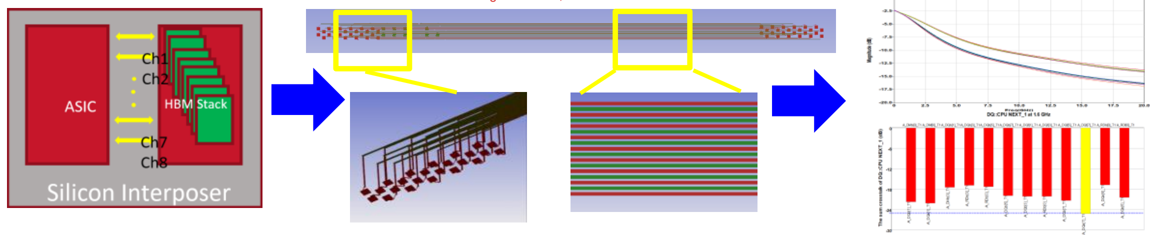
Interconnect Model Extraction

- Metis can extract interconnect model for both HBM and die-package TSV channels using one single solver without error-prone cut-and-stitch.
- It supports both GDS and ODB++ format.



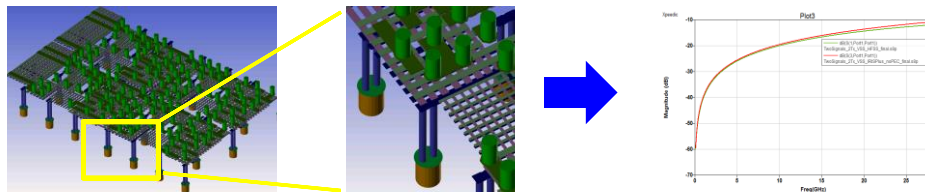
Interposer Routing Modeling

- HBM signals are transmitted between ASIC die and HBM stack. Metis enables users to achieve interposer modeling by a wizard, which helps users simulate channel's loss and crosstalk between different dies accurately.



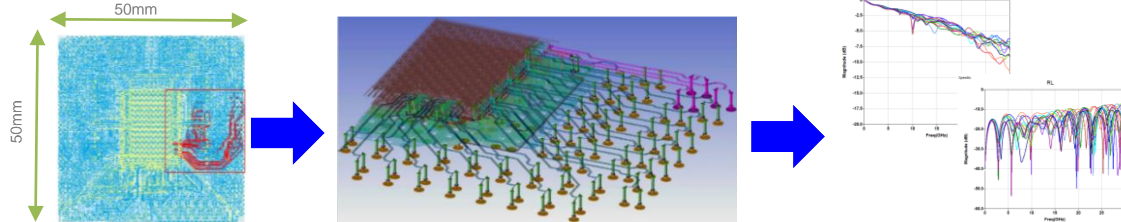
TSV Modeling

- Die-package channel with TSV is critical for channel performance due to the loss and crosstalk introduced by the TSVs. Metis can accurately extract the model for the die-package channel.



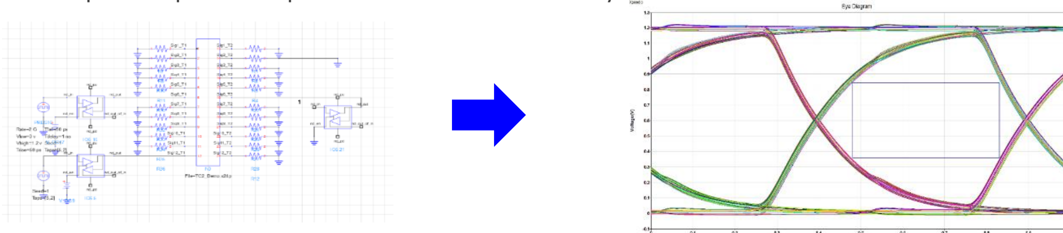
Package/Substrate Modeling

- For system SI and PI performance evaluation, transmission lines and power distribution networks on package substrate need accurate EM simulation. Metis provides a convenient simulation wizard for FCBGA package.



Channel Simulation

- ChannelExpert offers a quick way to build channel with the interconnect models extracted from Metis. By running the channel simulation, designers can check the performance with built-in compliance specs and optimize the channel if necessary.



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